| IPC ASSOCIATION ELECTRONICS  | © Copyright 2005.            | Material Composition Declaration  © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved und international and Pan-American copyright conventions. |                           |            | nder both                 | This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility. |                            |       |                    |                                 |                                 |                          |        |                   |      |  |
|------------------------------|------------------------------|---|---------------------------|------------|---------------------------|---|----------------------------|-------|--------------------|---------------------------------|---------------------------------|--------------------------|--------|-------------------|------|--|
| 1752-21.1                    |                              |   |                           |            | Form Type *<br>Distribute | Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Mater  |                            |       |                    |                                 | eous Materia                    | ials and Mfg Information |        |                   |      |  |
| Supplier                     | Information                  |   |                           |            |                           |   |                            |       |                    |                                 |                                 |                          |        |                   |      |  |
| Company name* Company unique |                              |   |                           | que ID Uni |                           | Unique ID Authority   |                            |       |                    |                                 | Response Date*                  |                          |        |                   |      |  |
| nsemi                        |                              |   |                           |            |                           |   |                            |       |                    |                                 | 2024-05-18                      |                          |        |                   |      |  |
| Contact Na                   | ame                          | Title - Contact   |                           |            | I                         | Phone - Contact*  |                            |       |                    | Email - Contact*                |                                 |                          |        |                   |      |  |
| Product-E                    | nv-Stewards                  | Product Enviro Compliance   |                           |            |                           | NA  |                            |       |                    | Product-Env-Stewards@onsemi.com |                                 |                          |        |                   |      |  |
| uthorized                    | l Representative*            | Title - Representative  |                           |            | I                         | Phone - Representative*   |                            |       |                    | Email - Representative*         |                                 |                          |        |                   |      |  |
| Product-Env-Stewards         |                              |   | Product Enviro Compliance |            |                           |   | NA                         |       |                    |                                 | Product-Env-Stewards@onsemi.com |                          |        |                   |      |  |
|                              | Requester Item Number Mfr    |   | Number                    |            |                           | Effective Date  | Versi                      | ion 1 | Manufacturing Site |                                 | \                               | Weight*                  | UOM    | Unit Type         |      |  |
|                              |                              | DF10S1 BR SDIP PN 1A  |                           | 1000V      |                           | 2024-05-18 PANJITFG   |                            | r     | 3                  | 310.0                           | mg                              | Each                     |        |                   |      |  |
|                              | eturing Process Informa      |   |                           |            |                           |   |                            | ·     |                    |                                 |                                 |                          |        | •                 |      |  |
|                              | <u> </u>                     |   | ,                         |            | -STD-020 MSL              | Rating  | Peak Process Body Temperat |       | · · ·              | •                               |                                 | Τ'                       |        | ber of Reflow Cyc | cles |  |
|                              | Matte Tin (Sn) - annealed    | (   | CU Alloy                  | 1          |                           |   | 260                        |       | C                  | 30                              |                                 | secon                    | ds   3 |                   |      |  |
| omments                      |                              |   |                           |            |                           |   |                            |       |                    |                                 |                                 |                          |        |                   |      |  |
|                              | aximum time at peak temperat |   |                           |            |                           |   |                            |       |                    |                                 |                                 |                          |        |                   |      |  |
| or more i                    | nformation regarding materia | l composition   | please refer to           | o page 3   |                           |   |                            |       |                    |                                 |                                 |                          |        |                   |      |  |

| <b>RoHS Material Composition Declaration</b>  |   |   | Declaration Type *          | Detailed   |  |  |  |  |  |  |
|---|---|---|-----------------------------|------------|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).   |   |   |                             |            |  |  |  |  |  |  |
| Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply. |   |   |                             |            |  |  |  |  |  |  |
| RoHS Declaration * 4 - Item(s   | s) does not contain RoHS restricted substance | ces per the definition above except for selected exer | nptions Supplier Acceptance | * Accepted |  |  |  |  |  |  |
| Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.   |   |   |                             |            |  |  |  |  |  |  |
| Exemption List Version  | EL-2011/534/EU                                |   |                             |            |  |  |  |  |  |  |
| Declaration Signature   |   |   |                             |            |  |  |  |  |  |  |
| Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.   |   |   |                             |            |  |  |  |  |  |  |
| Supplier Digital Signature R  |   | ,   |                             |            |  |  |  |  |  |  |

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

| Homogeneous Material | Weight  | Unit of Measure | Level    | Substance                  | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|---------|-----------------|----------|----------------------------|------------------|--------|---------|-----------------|
| Die                  | 3.6     | mg              | Supplier | Silicon (Si)               | 7440-21-3        |        | 3.3768  | mg              |
|                      |         |                 | В        | Nickel (Ni)                | 7440-02-0        |        | 0.0324  | mg              |
|                      |         |                 | Supplier | Gold (Au)                  | 7440-57-5        |        | 0.018   | mg              |
|                      |         |                 | A        | Lead Oxide (PbO)           | 1317-36-8        | 7c     | 0.1728  | mg              |
| Die Attach Solder    | 2.595   | mg              | Supplier | Silver (Ag)                | 7440-22-4        |        | 0.0649  | mg              |
|                      |         |                 | A        | Lead (Pb)                  | 7439-92-1        | 7a     | 2.4004  | mg              |
|                      |         |                 | Supplier | Tin (Sn)                   | 7440-31-5        |        | 0.1297  | mg              |
| Lead Frame           | 63.63   | mg              | Supplier | Iron (Fe)                  | 7439-89-6        |        | 0.0764  | mg              |
|                      |         |                 | Supplier | Copper (Cu)                | 7440-50-8        |        | 63.5346 | mg              |
|                      |         |                 | Supplier | Phosphorus (P)             | 7723-14-0        |        | 0.0191  | mg              |
| Mold Compound-Black  | 233.175 | mg              |          | Metal Hydroxide            | proprietary data |        | 8.1611  | mg              |
|                      |         |                 | Supplier | Ortho Cresol Novolac Resin | 29690-82-2       |        | 18.654  | mg              |
|                      |         |                 | Supplier | Carbon Black (C)           | 1333-86-4        |        | 1.1659  | mg              |
|                      |         |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0       |        | 186.54  | mg              |
|                      |         |                 | Supplier | Phenolic Resin (Novolac)   | 9003-35-4        |        | 18.654  | mg              |
| Plating              | 7.0     | mg              | Supplier | Tin (Sn)                   | 7440-31-5        |        | 7       | mg              |